- 1. (Original) A wafer half-shell having a mouth delimited by at least one annular surface and one or more side walls, in which the mouth annular surface and the surfaces of the side wall have a substantially smooth surface finish, wherein the outer surface of the side wall has a porous, continuous or discontinuous region which extends peripherally and is receded relative to the mouth annular surface of the half-shell.
- 2. (Original) A half-shell according to Claim 1, wherein the porous region is the surface resulting from the cutting of one or more radial walls connected to the side wall of the half-shell in a receded position relative to the annular surface defining the mouth of the half-shell.
- 3. (Original) A half-shell according to Claim 2, obtained by cutting from an intermediate wafer comprising a plurality of half-shells interconnected by at least one interconnecting wall extending from the side wall of each half-shell and connected to the half-shells in a receded position relative to the annular mouth surface.
- 4. (Original) A half-shell according to Claim 1, wherein said annular surface comprises centering means adapted to fit with complementary centering means of a complementary half-shell.
- 5. (Original) A half-shell according to Claim 4, wherein said centering means comprise tapered annular coupling surfaces or coupling surfaces having a U, V, L-shaped profile or a toothed, Greek-key pattern or zigzag profile.
- 6. (Original) A wafer comprising a plurality of half-shells with at least one containing side wall and interconnected by at

least one interconnecting wall, wherein the interconnecting wall is connected to the half-shells in a receded position relative to the annular mouth surface of each half-shell.

- 7. (Original) A wafer according to Claim 6, wherein the half-shells are interconnected by means of a plurality of interconnecting walls (8a, 8b) which extend from the containing side walls (10) of the half-shells.
- 8. (Original) A food product comprising a half-shell according to Claim 1 and including a mass of filling contained in the half-shell.
- 9. (Currently Amended) A food product according to Claim 8, comprising a pair of half-shells, fitted together mouth to mouth and including a mass of filling, wherein at least one of the half-shells is a wafer half-shell having a mouth delimited by at least one annular surface and one or more side walls, in which the mouth annular surface and the surfaces of the side wall have a substantially smooth surface finish, wherein the outer surface of the side wall has a porous, continuous or discontinuous region which extends peripherally and is receded relative to the mouth annular surface of the half-shell. according to any one of Claims 1 to 5.
- 10. (Original) A food product comprising at least two wafer half-shells coupled one to the other along annular mating surfaces defining their mouth profile, wherein said annular mating surfaces of each of said half-shells have centering means complementary one to the other.
- 11. (Original) A food product according to Claim 10, wherein said centering means comprise formations susceptible of mutual engagement.

- 12. (Currently Amended) A food product according to Claims 10 or 11, wherein said centering means comprise annular mating surfaces having a toothed profile, a U-shaped profile, a V-shaped profile, a L-shaped profile, a Greek-key pattern profile or a zigzag profile.
- 13. (Currently Amended) A food product according to Claims 10 or 11, wherein said centering means comprise tapered annular mating surfaces.
- 14. (Original) A food product according to Claim 10, wherein at least one of said half-shells has a sidewall with a porous, continuous or discontinuous region extending peripherally, which is receded relative to the mating annular surface of said half-shell.
- 15. (Original) A food product according to claim 10, wherein said annular mating surfaces and the surface of said centering means have a smooth surface finish.
- 16. (Original) A method for the preparation of a wafer half-shell with a mouth and a containing side wall, comprising the steps of:
- preparing a wafer comprising a plurality of the half-shells connected by at least one interconnecting wall connected to the half-shells in a receded position relative to the annular mouth surface of the half-shells, and
- separating the individual half-shells from the interconnecting wall by cutting in a direction perpendicular to the general plane of the interconnecting wall.
- 17. (Original) A method according to Claim 15, wherein the wafer is a product produced by baking a wafer batter in a mould.